In the specification:

Please amend the paragraph beginning at page 1, line 6 as follows:

-- This application claims priority under 35 USC is a continuation-in-part of U.S. Patent Application Serial No. 09/741,535, filed on December [29] 19, 2000, the entire contents of which are hereby incorporated by reference. --

Please amend the paragraph beginning at page 4, line 8 as follows:

-- Figure 4 is a schematic of a process of packaging [dies 101. The process includes dicing the substrate 105.] a die using a half-etched lead frame 105. --

Please amend the paragraph beginning at page 4, line 10 as follows:

-- Figure 5 is a schematic of a process of packaging dies 101. The process includes dicing the substrate 105. [a flow chart for a process of packaging a die 101.] --

Please amend the paragraph beginning at page 4, line 12 as follows:

-- Figure 6 is a flow chart for a process of packaging a die 101. [schematic of a process of packaging a die using a half-etched lead frame 105] --

Please amend the paragraph beginning at page 13, line 25 as follows:

-- In another implementation, as depicted in Figure [6]4A, a half-etched substrate 705 is used. For a substrate having a thickness of about 18 μm, half-etches 710 are created that are about 9 μm deep and that are backed by an underlayer 730 of the substrate 705. Referring to Figure [6]4B, the die 101 is disposed on the half-etched substrate 705 such that the die bumps 110 form interconnects along ridges 720 of the half-etched substrate 705. Referring to Figure [6]4C, the assembly is contacted with the polymer composition to form a network 150 that rigidifies and strengthens the assembly. Referring to Figure [6]4D, the bottom half or substrate underlayer 730 of the half-etched substrate 705 is then removed in order to fabricate the lead frame 210. --